

Title (en)

MICRO-ELECTROMECHANICAL DEVICES AND METHODS OF MANUFACTURE

Title (de)

MIKROELEKTROMECHANISCHE BAUELEMENTE UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

DISPOSITIFS MICROELECTRIQUES ET LEURS PROCEDES DE FABRICATION

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Application

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Abstract (en)

[origin: WO0100523A1] Micro-electromechanical devices, substrate assemblies from which the devices can be manufactured, and methods to manufacture the devices are disclosed. The invention combines the advantages of conventional surface and bulk micromachining processes using a sacrificial layer to create an integrated micro-electromechanical system (MEMS) technology that provides high performance, high yield, and manufacturing tolerance. The devices manufactured according to the present invention include, but are not limited to, pressure sensors, vibration sensors, accelerometers, gas or liquid pumps, flow sensor, resonant devices, and infrared detectors.

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